ADAS CAMERAS AND LIDARS

LOCTITE® 3296

Next generation, fast dual cure, **active alignment adhesive** for automotive optical sensors offering high glass transition temperature (Tg) and low coefficient of thermal expansion (CTE), low and consistent shrinkage, and very low outgassing with excellent adhesion to standard substrates like aluminum and FR4.

LOCTITE® ABLESTIK NCA 3218

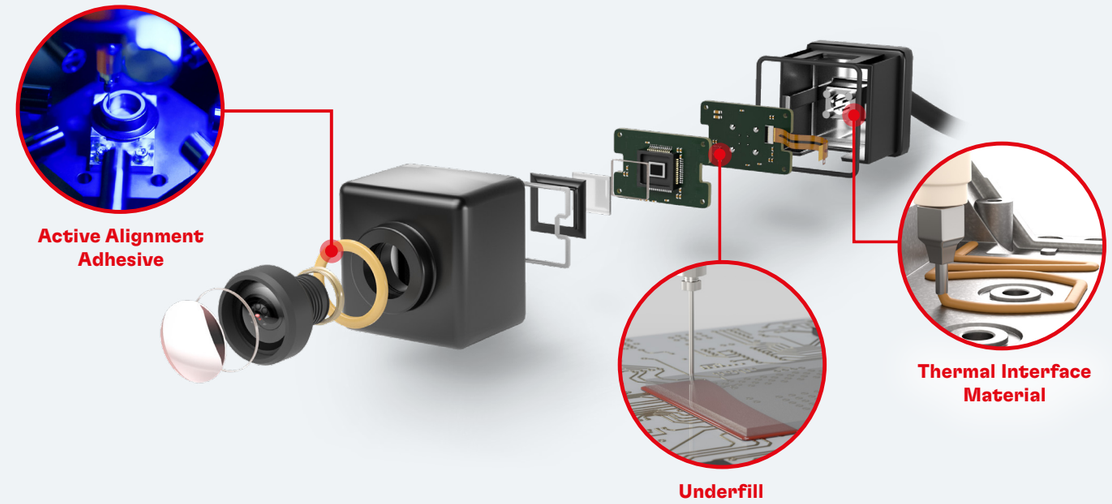
Next generation, dual cure, **active alignment adhesive** offering high glass transition temperature (Tg) and low coefficient of thermal expansion (CTE), low and consistent shrinkage, and very low outgassing with excellent adhesion to PCB and various substrates like PPS and PBT. Its gray color prevents unintended light penetration.

BERGQUIST LIQUI FORM TLF 4500CGEL-SF

Silicone-free, 1-component curable gel with 4.5 W/mK thermal conductivity. **Thermal interface material** optimized for optical systems passing hazing, fogging, and outgassing tests. Fast dispense and reliable vertical gap stability.

Highlighted products and applications are not exhaustive. Please refer to full product portfolio from page 28 and forward for more information.

CAMERA



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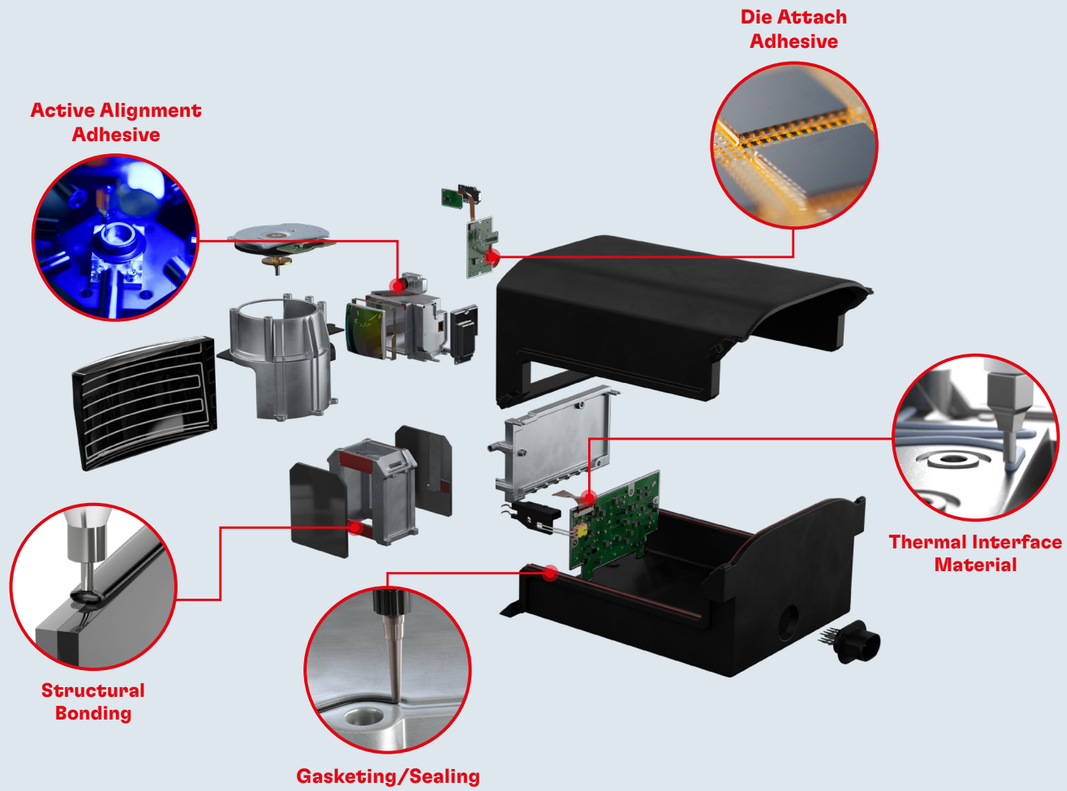
LIDAR



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ADAS RADARS

BERGQUIST GAP PAD TGP EMI 4000

Multifunctional, silicone-free, highly conformable gap pad with 4.0 W/mK thermal conductivity combined with electromagnetic energy absorption at frequencies up to 77GHz. **EMI protection** and **thermal management** in one product.

LOCTITE® SI 5972 FC

1-component silicone-based, formed-in-place **gasketing** material (FIPG) that enables a fast process cycle during gasketing with excellent adhesion to aluminum and most plastics.

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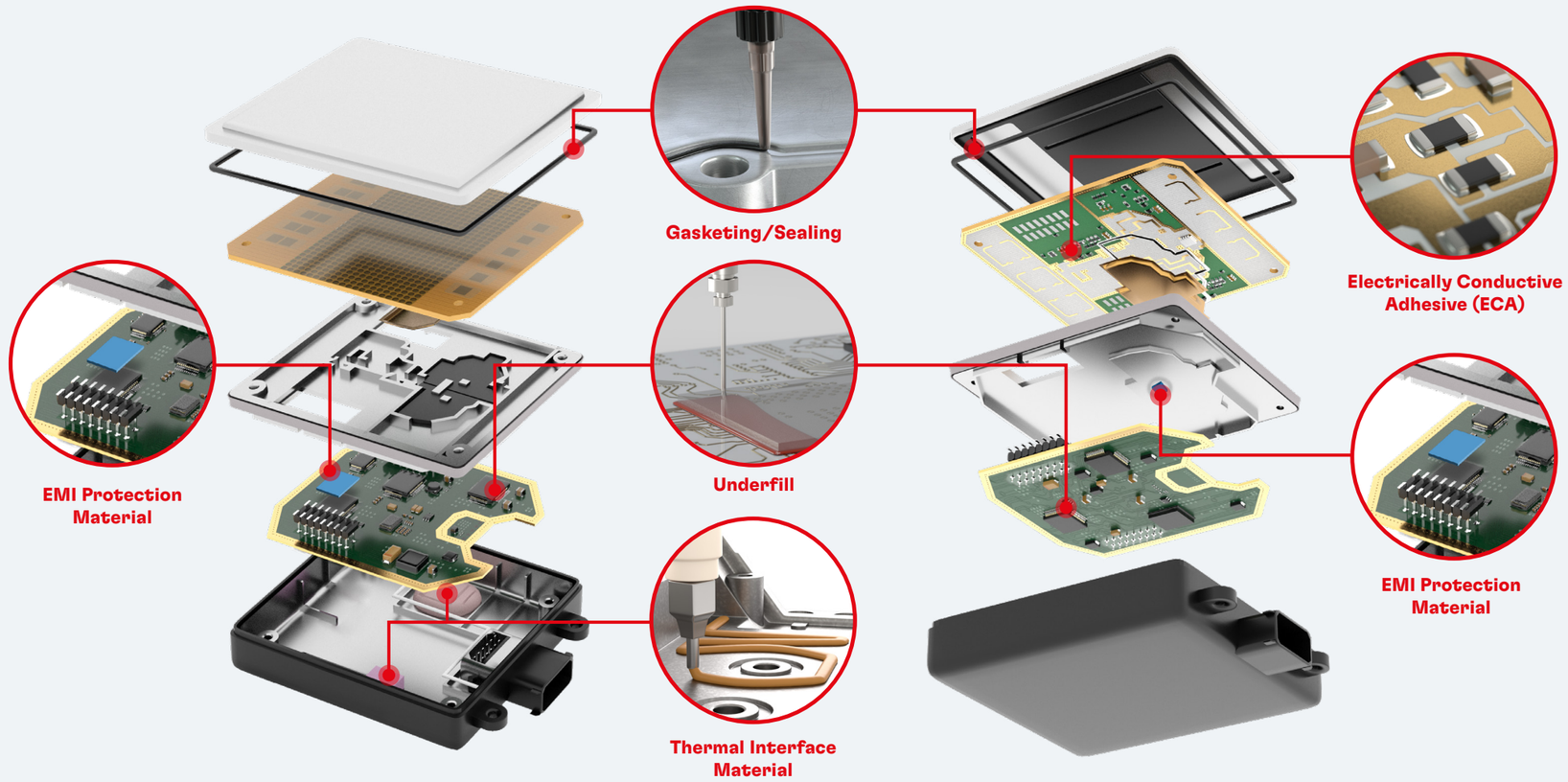
RADAR



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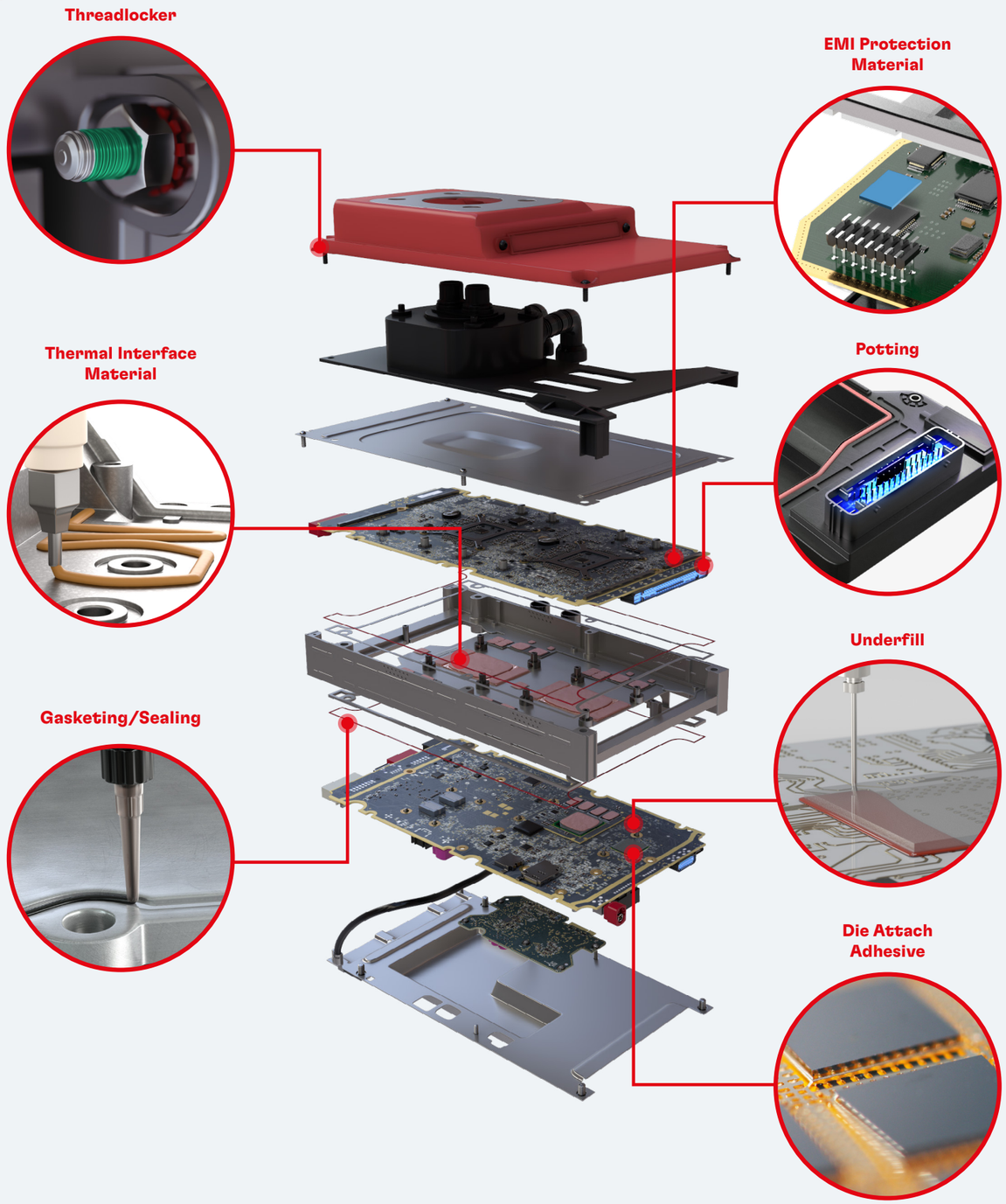
ADAS CONTROL MODULES

LOCTITE® ECCOBOND UF 1173

Epoxy-based full capillary board level **underfill** with high glass transition temperature (Tg) of 159°C and low coefficient of thermal expansion (CTE) that offers uniform and void-free reinforced solder joint reliability in CSP and BGA packages at high operating temperatures, while prioritizing health and safety based on a CMR-free formulation.

Highlighted products and applications are not exhaustive. Please refer to full product portfolio from page 28 and forward for more information.

ADAS CONTROL MODULE



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